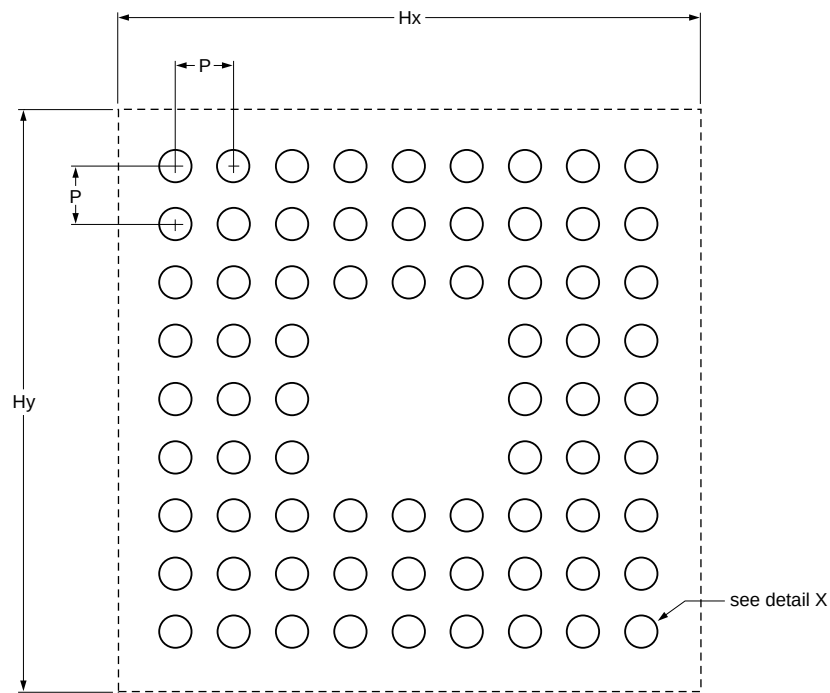


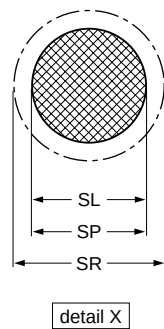
Footprint information for reflow soldering of HBGA520 package

SOT1088-1



Generic footprint pattern
Refer to the package outline drawing for actual layout

-  solder land
-  solder paste deposit
-  solder land plus solder paste
-  occupied area
-  solder resist



DIMENSIONS in mm

P	SL	SP	SR	Hx	Hy
1.00	0.450	0.450	0.600	27.500	27.500